

116-93-636-41-006000

116-93-636-41-006000 Information

Heisener.com	 116-93-636-41-006000 Mill-Max Manufacturing Corp. Connectors, Interconnects Sockets for ICs, Transistors CONN IC DIP SOCKET 36POS GOLD - For the pricing/inventory/lead time, please contact	
For Reference Only	us Website: https://www.heisener.com E-mail: salesdept@heisener.com	Request a Quote

Certified Quality

Heisener's commitment to quality has shaped our processes for sourcing, testing, shipping, and every step in between. This foundation underlies each component we sell.



116-93-636-41-006000 Specifications

Manufacturer Part Number 116-93-636-41-006000 Manufacturer Kill-Max Manufacturing Corp. Category Connectors, Interconnects Sockets for ICs, Transistors Sockets for ICs, Transistors Package - Series 116 Type DIP, 0.6" (15.24mm) Row Spacing Number of Positions or Pins (Grid) 36 (2 x 18) Pitch - Mating 0.100" (2.54mm) Contact Finish - Mating Gold Contact Finish Thickness - Mating 30µin (0.76µm) Contact Finish - Mating Beryllium Copper Mounting Type Through Hole Features Elevated, Open Frame Termination Solder Pitch - Post 0.100" (2.54mm) Contact Finish - Post Solder Contact Finish - Post Brass Alloy			
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Housing MaterialPolycyclohexylenedimethylene Terephthalate (PCT), PolyesterOperating Temperature-55°C ~ 125°C	Contact Finish Thickness - Post	200µin (5.08µm)	
Operating Temperature $-55^{\circ}C \sim 125^{\circ}C$	Contact Material - Post	Brass Alloy	
	Housing Material	Polycyclohexylenedimethylene Terephthalate (PCT), Polyester	
Report errors?	Operating Temperature	-55°C ~ 125°C	
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116-93-636-41-006000 Guarantees



Quality Guarantees

We provide 90 days warranty. * If the items you received were not in perfect quality, we would be responsible for your refund or replacement, but the items must be returned in their original condition.

SERVICE BUARANTEE

Service Guarantees

We guarantee 100% customer satisfaction. Our experienced sales team and tech support team back our services to satisfy all our customers.

DISCOVER

116-93-636-41-006000 Payment Methods

116-93-636-41-006000 Shipping Methods



If you have any question about 116-93-636-41-006000, please do not hesitate to contact us! Website: https://www.heisener.com E-mail: salesdept@heisener.com